PRODUCT SELECTOR GUIDE

PART NUMBER	CATALOG NAME	CAS / TSCA Listed (Y/N)	DESCRIPTION	STRUCTURE **	FEATURES	APPEARANCE	VISCOSITY (cP @ 25°C)	SUGGESTED APPLICATIONS
ANTI-BLEEDS								
A6150	A-6150	1151519-17-3 (Y)	A proprietary **non-halogenated** additive designed to reduce resin bleed out on a variety of surfaces (especially difficult to control copper surfaces) with minimal or no effect on the adhesion properties of the formulation.	Unavailable	• Excellent bleed control • Co-curable in free-radical polymerization • Minimal adhesion degradation • Non-halogenated– a 'green' alternative to conventional anti-bleed and mold release materials	Yellow Liquid	100	For use as an additive to reduce resin bleed out specifically on metal surfaces
A6225	A-6225	2247074-15-1 (Y)	Antibleed Additive – Silicone Mercapto Propionate (SMP). A proprietary non halogenated additive designed to reduce resin bleed out on a variety of surfaces (especially difficult to control gold surfaces) with minimal or no effect on the adhesion properties of the formulation.	Unavailable	• Excellent bleed control • Co-curable in most systems • Minimal adhesion degradation • Non-halogenated– a 'green' alternative to conventional anti-bleed and mold release materials	Colorless Liquid	50	For use as an additive to reduce resin bleed out specifically on metal surfaces
A6265	A-6265	2225898-70-2 (LVE)	A proprietary **non-halogenated** additive designed to reduce resin bleed out on a variety of surfaces with minimal or no effect on the adhesion properties of the formulation.	Unavailable	• Excellent bleed control • Co-curable in free-radical polymerization • Minimal adhesion degradation • Non-halogenated– a 'green' alternative to conventional anti-bleed and mold release materials	Clear, Colorless to Light Yellow Liquid	500	For use as an additive to reduce resin bleed out specifically on metal surfaces
A6280	A-6280	2999663-83-9 (N)	A proprietary **non-halogenated** additive designed to reduce resin bleed out on a variety of surfaces (especially difficult to control gold surfaces) with minimal or no effect on the adhesion properties of the formulation.	Unavailable	• Excellent bleed control • Co-curable in free-radical polymerization • Minimal adhesion degradation • Non-halogenated – a 'green' alternative to conventional anti-bleed and mold release materials	Yellow Liquid	63	For use as an additive to reduce resin bleed out specifically on metal surfaces

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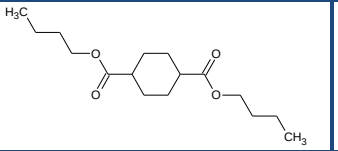
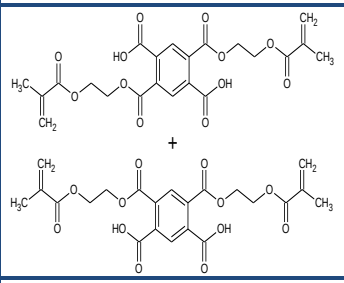
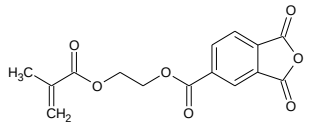
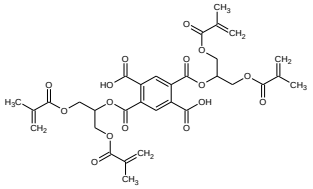
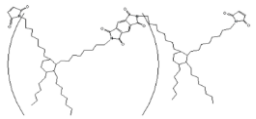
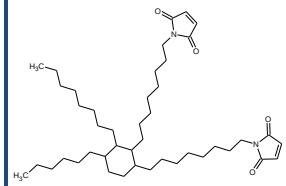
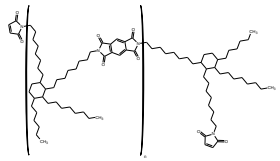
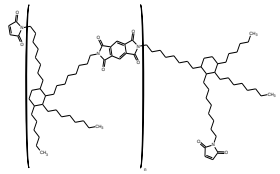
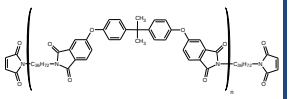
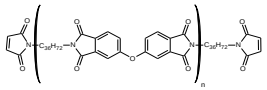
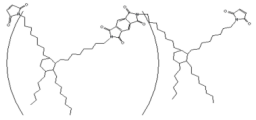
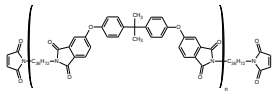
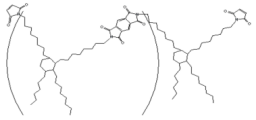
FUNCTIONAL ADDITIVES								
A6165	A-6165	1151654-51-1 (Y)	Soluble additive that on addition to a conductive adhesive formulation can significantly decrease the volume resistivity of the cured material	Unavailable	• Improves electrical conductivity in metal filed conductive paste formulations • Soluble in most resin systems • May improve thermal conductivity in some formulations	Dark Brown / Black	Very viscous	• Increases electrical conductivity of resin system
A6220	A-284	93158-39-5 (Y)	Dibutyl-1,4 Cyclohexanedicarboxylate		• Plasticizer • Non-phthalate • Very low viscosity	Colorless Liquid	30	• For use as a plasticizer in applications where human contact is expected
R1217-M	A-478-M	111308-10-2 (N)	Pyromellitic Dianhydride Dimethacrylate – Mixture of Isomers		• Versatile adhesion promoter	Fine White Powder	Solid	• Adhesion promoter
R1231	A-304	70293-55-9 (N)	4-Metacryloxyethyl Trimellitic Anhydride		• Adhesion Promoter • Versatile adhesion promoter	White Powder / Crystals	Solid	• Adhesion promoter
R1251	A-675-100%	148019-46-9 (Y)	PMGDM		• Versatile adhesion promoter	Light Yellow	Very viscous	• Adhesion promoter

PRODUCT SELECTOR GUIDE

PART NUMBER	CATALOG NAME	CAS / TSCA Listed (Y/N)	DESCRIPTION	STRUCTURE **	FEATURES	CAVITY PERTURBATION METHOD @ 20 GHZ	APPEARANCE	VISCOSITY (cP @ 25°C)	SUGGESTED APPLICATIONS
IMIDE-EXTENDED BISMALEIMIDES									
R1090	BMI-3000 Gel	921213-77-6 (Y)	Bismaleimide oligomer that exhibits excellent flexibility and, on cure, forms very tough hydrophobic polyimides.	 Where n = 1 to 10	• Toughener • Hydrophobic • High adhesion * • Superior thermal stability	Dk : N/A Df : N/A	Red-Amber Gel	Solid	• Film adhesives • Pre-applied adhesives • Adhesion to metal
R1155	BMI-689	Original: 682800-79-9 Current: 1911605-95-2 (Y)	A unique very low viscosity BMI resin	 contains unsaturation	• Toughener • Hydrophobic • High adhesion * • Superior thermal stability	Dk : 2.4 Df : 0.0023	Yellow to Amber Liquid	1,500 ± 500	• Base resin or additive in thermoset formulations designed for high temperature resistance
R1171-P	BMI-5000 Powder	921213-77-6 (Y)	Imide-extended bismaleimide oligomer that exhibits excellent toughness in the cured state with intermediate cross-link density.	 Where n = 1 to 10	• Low cross-link density • Non-tacky • Film-forming • Maleimide functional oligomer • Cures to a tough thermoset • Additive to enhance toughness in thermoset compositions	Dk : 2.4 Df : 0.0023	Light Yellow Powder	Solid	• Film adhesives • Thermally resistant adhesives
R1171-T	BMI-5000 Toluene	921213-77-6 (Y)	Imide-extended bismaleimide oligomer that exhibits excellent toughness in the cured state with intermediate cross-link density.	 Where n = 1 to 10	• Low cross-link density • Non-tacky • Film-forming • Maleimide functional oligomer • Cures to a tough thermoset • Additive to enhance toughness in thermoset compositions	Dk : 2.4 Df : 0.0023	Dark Brown Liquid	1,000	• Film adhesives • Thermally resistant adhesives

PART NUMBER	CATALOG NAME	CAS / TSCA Listed (Y/N)	DESCRIPTION	STRUCTURE **	FEATURES	CAVITY PERTURBATION METHOD @ 20 GHZ	APPEARANCE	VISCOSITY (cP @ 25°C)	SUGGESTED APPLICATIONS
IMIDE-EXTENDED BISMALEIMIDES continued…									
R1191	BMI-1700	1224691-98-8 (Y)	An amorphous, low molecular weight bismaleimide oligomer that exhibits good adhesion to a variety of substrates	 Where n = 1 to 10	• Soluble in many reactive diluents • Hydrophobic • Superior thermal stability • High adhesion to various substrates	Dk : 2.3 Df : 0.00176	Amber High Viscous Liquid	30,000 ± 10,000 (60°C)	• Film adhesives • Pre-applied adhesives • Adhesion to metal
R1203	BMI-1500	1290041-56-3 (Y)	An amorphous, low molecular weight bismaleimide oligomer that exhibits good adhesion to a variety of substrates	 Where n = 1 to 10	• Soluble in many reactive diluents • Hydrophobic • Superior thermal stability • High adhesion to various substrates	Dk : 2.42 Df : 0.0021	Amber Viscous Liquid	20,000 ± 10,000 (60°C)	• Film adhesives • Pre-applied adhesives • Adhesion to metal
R1225	BMI-3000 CG	921213-77-6 (Y)	Low cost bismaleimide oligomer that exhibits excellent flexibility and, on cure, forms very tough hydrophobic polyimides.	 Where n = 1 to 10	• Low cost • Toughener • Hydrophobic • High adhesion * • Superior thermal stability	Dk : 2.34 Df : 0.0016	Light Yellow Powder	Solid	• Film adhesives • Pre-applied adhesives • Adhesion to metal
R1232	BMI-1400	1224691-98-8 (Y)	An amorphous, low molecular weight bismaleimide oligomer that exhibits good adhesion to a variety of substrates	 Where n = 1 to 10	• Specialty formulated lower viscosity version of BMI-1700	Dk : 2.3 Df : 0.00245	Amber High Viscous Liquid	6,500 ± 1,000 (60°C)	• Film adhesives • Pre-applied adhesives • Adhesion to metal
R1288	BMI-3000J Powder	921213-77-6 (Y)	Bismaleimide oligomer that exhibits excellent flexibility and, on cure, forms very tough hydrophobic polyimides	 Where n = 1 to 10	• Toughener • Hydrophobic • High adhesion * • Superior thermal stability	Dk : 2.195 Df : 0.00136	Light Yellow Powder	Solid	• Film adhesives • Pre-applied adhesives • Adhesion to metal

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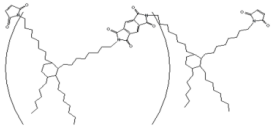
IMIDE-EXTENDED BISMALEIMIDES continued…									
R1288S	BMI-3000 Solution	921213-77-6 (Y)	Bismaleimide oligomer that exhibits excellent flexibility and, on cure, forms very tough hydrophobic polyimides	 Where n = 1 to 10	• Toughener • Hydrophobic • Excellent dielectric properties • Superior thermal stability	Dk : 2.4 Df : 0.0017	Light Amber Liquid	N/A	• Additive to increase flexibility, hydrophobicity and thixotropy.
R1316	BMI-2500	2020378-57-6 (Y)	Designed to extend the range of applications suitable for use with Designer Molecules, Inc. Imide-Extended Bismaleimide Oligomers to those in need of higher Tg and modulus.	N/A	• Toughener • Hydrophobic • High adhesion * • Superior thermal stability • Low pH hydrolytic resistance • Reduce resin bleed out	Dk : 2.3 Df : 0.0015	Light Yellow Glassy Powder	Solid	• Additive to increase flexibility, hydrophobicity, thixotropy • Base resin – produces films that are tough, flexible, & have good peel strength
R1334	BMI-6000	2095324-53-9 (N)	Has excellent thermal stability and workability. It is soluble in a variety of solvents such as cyclopentanone, cyclohexanone, MEK, DMF, DMAC, and NMP in combination with aromatic solvents	N/A	• Toughener • Hydrophobic • Super thermal stability • Good dielectric properties • Excellent workability • High Tg • Low CTE	Dk : 2.6 Df : 0.008	Light yellow powder	Solid	• Adhesive layer when laminating materials • Adhesion promoter
R1354	BMI-2560	2126832-79-7 (N)	Designed to extend the range of applications suitable for use with the Designer Molecules, Inc. imide extended bismaleimide oligomers to those in need of higher Tg and modulus	N/A	• Toughener • Hydrophobic • Superior thermal stability	Dk : 2.5 Df : 0.0016	Light Yellow Glassy Powder	Solid	• An additive to increase flexibility, hydrophobicity and thixotropy

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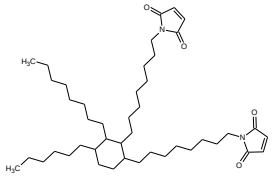
IMIDE-EXTENDED BISMALEIMIDES continued…									
R1356	BMI-6100	2127116-97-4 (N)	A high molecular weight, curable bismaleimide (BMI) oligomer mixture suitable for use as the base resin in a variety of microelectronic assembly applications	N/A	• Flexibility / High strength • Curability / Hydrophobicity • Superior electrical properties	Dk : 2.65 Df : 0.005	Amber liquid	370	• Recommended for use as a polyimide (PI) replacement resin in CCL applications
R1442	BMI-689M	1911605-95-2 (Y)	A unique low viscosity liquid bismaleimide based on a non-hydrogenated dimer diamine backbone and serves as a low-cost alternative to DMI's BMI-689	 contains unsaturation	• Low viscosity liquid BMI • Hydrophobic • Superior thermal stability	Dk : 2.4 Df : 0.0023	Dark amber liquid	5,000 ± 2,000	• An additive or base resin in adhesives that are designed for high temperature resistance
R1453	BMI-4200	N/A (N)	Designed to extend the range of applications suitable for use with DMI's imide extended BMI oligomers to those in need of a higher Tg and modulus. It can be processed in a resin system as a solid or dissolved in a solvent.	N/A	• Toughener • Hydrophobic • Increased Tg & modulus for demanding applications • Superior thermal stability	Dk : 2.64 Df : 0.00206	Yellow granules	Solid	• An additive to increase hydrophobicity and thixotropy

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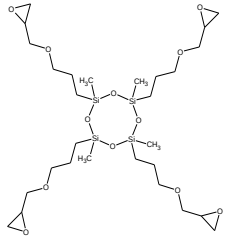
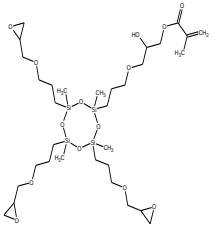
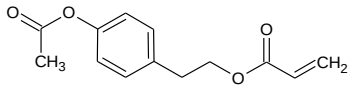
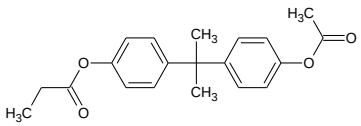
FUNCTIONAL CYCLOSILOXANES								
R1362	CS-697	257284-60-9 (Y)	A polyglycidyl ether cyclosiloxane monomer		• Multifunctional • UV curable • Low chloride • Low viscosity • Colorless	Colorless Liquid	200	• UV curable additive
R1366	CS-783	921214-21-3 (Y)	Methacrylate epoxy functional hybrid cyclosiloxane monomer		• Dual cure mechanism • Multifunctional • UV Curable • Low chloride • Low viscosity	Yellow Liquid	250	• Hybrid cures • UV cures • B-stageable adhesives
PHENYL ESTER EPOXY CURATIVES								
R1146	EC-234	926305-16-0 (Y-LVE)	Phenyl ester epoxy curative hybrid		• Hybrid cure • Low viscosity	Light Yellow Liquid	40	• UV adhesives • B-stageable adhesives
R1147	EC-326	936555-33-8 (Y-LVE)	Bisphenol A based acetate/proprionate epoxy curative		• Hydrolytically resistant • Low melting point • Thermal stability • Hydrophobic • Toughener • Does not impede free radical cure	White/Yellow Solid	2,000 ***	• Film adhesives • Pre-applied adhesives

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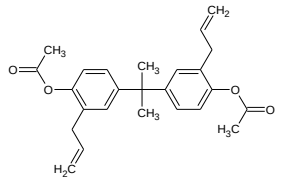
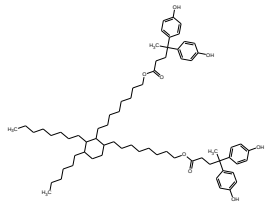
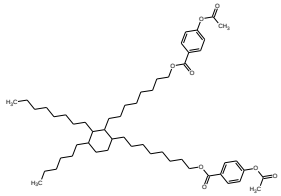
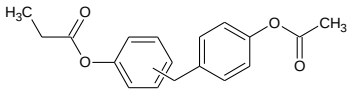
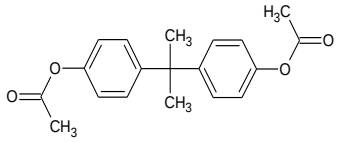
PHENYL ESTER EPOXY CURATIVES continued…								
R1148	EC-392	107466-61-9 (Y)	Phenyl ester epoxy curative hybrid of diallyl bisphenol A		• Dual cure mechanism • High cross-link density • Multifunctional • Thermal stability	Amber Liquid	2,500	• B-stageable adhesives • Epoxy and BMI co-curative
R1149	EC-1074	926657-64-9 (Y)	A tetra-phenol epoxy curative derived from dimerdiol		• Low modulus • Toughener • Hydrolytically resistant thermosets • Hydrophobic • Thermal stability	Amber Glassy Solid	Solid	• Film Adhesives • Pre-applied adhesive compositions
R1165	EC-861	1071523-12-0 (Y)	Phenyl acetate epoxy curative		• Low modulus • Toughener • Hydrolytically resistant thermosets • Hydrophobic • Thermal stability • Does not impede free radical cure	Amber/Yellow Liquid	2,500	• Low stress epoxy thermosets
R1170	EC-298	1044794-71-7 (Y-LVE)	Difunctional phenyl ester epoxy curative		• Stable • Low viscosity • Does not impede free radical cure	Light Yellow Liquid	500	• Thermoset adhesives • Curative for epoxy /(meth)acrylate hybrids • Hybrid epoxy/free radical thermosets
R1227	EC-312	10192-62-8 (Y)	Difunctional phenyl ester epoxy curative		• Low cost • Low melting point • Thermal stability • Hydrophobic • Does not impede free radical cure	Fine White Powder	Solid	• Film adhesives • Pre-applied adhesives

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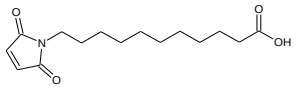
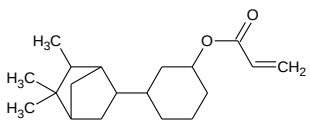
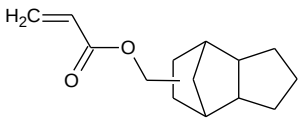
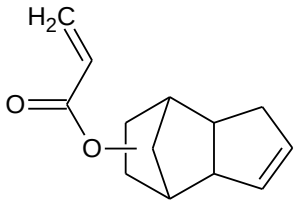
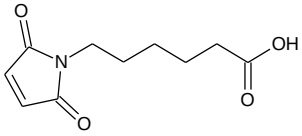
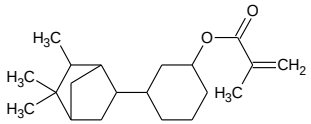
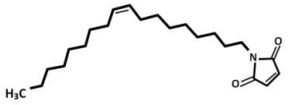
EPOXY CATALYSTS								
R1198 **R1207** **R1208** **R1209**	**ECAT Series** ECAT-243 ECAT-259 ECAT-353 ECAT-434	1253404-90-8 (Y) 1313999-39-1 (Y) 1325729-75-6 (Y) 1332716-20-7 (Y)	Imidazole Epoxy Catalysts	Unavailable	• Good solubility in most epoxy monomers • Excellent latency characteristics • Can be used as a catalyst or curative • Tunable cures • Promotes clean, rapid monomodal cures	Refer to TDS	Solid	• Electronic mold compounds • Underfills
MONOFUNCTIONAL MONOMERS								
R1121	MM-281	57079-01-3 (Y-LVE)	Maleimidoundecanoic Acid (MUDA)		• Flexible aliphatic backbone • Maleimide & carboxylic acid functional groups • Adhesion promoter	White to Off-white Powder	N/A	• Intermediate for ester and amide linked maleimide monomers
R1134	MM-290	903876-45-9 (Y)	Isobornyl Cyclohexyl Acrylate		• Lower weight loss on cure than Isobornyl Acrylate (IBOA) • Mild, pleasant odor • Hydrolytic resistance	Light Tan Liquid	250	• UV or peroxide cured resins, coatings, or adhesives
R1139	MM-220	93962-84-6 (Y-LVE)	Tricyclodecane Acrylate		• Low weight loss on cure • Helps reduce cure shrinkage • Low viscosity	Light Yellow Liquid	< 100	• UV cure coatings

PART NUMBER	CATALOG NAME	CAS / TSCA Listed (Y/N)	DESCRIPTION	STRUCTURE **	FEATURES	APPEARANCE	VISCOSITY (cP @ 25°C)	SUGGESTED APPLICATIONS
MONOFUNCTIONAL MONOMERS continued…								
R1173	MM-204	33791-58-1 (Y)	Monofunctional acrylate monomer		• Low viscosity • High glass transition temperature • Low cure shrinkage • Hydrolytically resistant • Diluent for thermoset resins • High Tg	Light Tan Liquid	50	• UV or peroxide cured resins, coatings, or adhesives
R1175	MM-211	55750-53-3 (N)	An intermediate chain length, maleimide terminated carboxylic acid		• Flexible aliphatic backbone • Maleimide and carboxylic acid functional groups • Adhesion promoter	White/Light Yellow Powder	N/A	• Intermediate for ester and amide linked maleimide monomers
R1197	MM-304	N/A (N)	Isobornyl Cyclohexyl Methacrylate		• Very low color • Lower weight loss on cure than Isobornyl Methacrylate (IBOMA) • Mild, pleasant odor • Hydrolytic resistance	Colorless Liquid	80	• Dental • Reactive diluent
R1233	MM-348	132010-64-1 (N)	Maleimide Terminated 9-Octadecene		• Maleimide functional reactive diluents	Light brown	Semi-solid	• Reactive diluent

PRODUCT SELECTOR GUIDE

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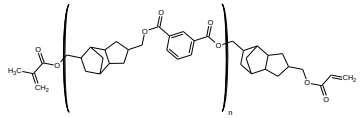
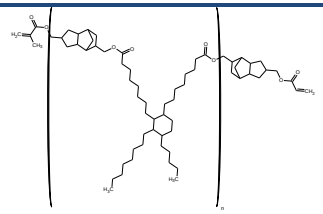
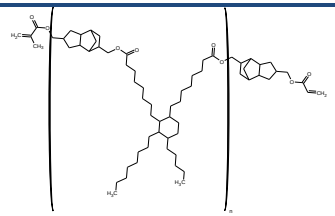
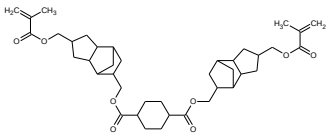
POLYESTER ACRYLATE METHACRYLATES (PEAM)								
R1096	PEAM-645	921213-39-0 (Y)	Polyester Acrylate/Methacrylate	 Where n = 1 to 5	• High Tg • High modulus • Low CTE • High adhesion I • Thermal stability	Amber Liquid	6,500	• Low CTE thermosets
R1111	PEAM-1044	921214-61-1 (Y)	Polyester Acrylate/Methacrylate	 Where n = 1 to 5	• Low warpage • Hydrophobic • High adhesion * • Thermal stability	Amber Liquid	(40°C)	• Low stress coatings
R1144	PEAM-1769	921214-61-1 (Y)	Polyester Acrylate/Methacrylate	 Where n = 1 to 5	• Ultra-low modulus • Hydrophobic • High adhesion * • High thermal stability • Adhesion to metals • Flexibilizer	Amber Liquid	4,500	• Low stress coatings
POLYESTER METHACRYLATES (PEM)								
R9990	PEM-665	N/A (N)	Methacrylate terminated polyester oligomer		• Low color • Low cure shrinkage • Thermal stability • Tough	Light Yellow Tint Liquid	6,500 (50°C)	• Dental BisGMA replacement

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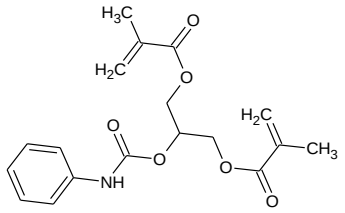
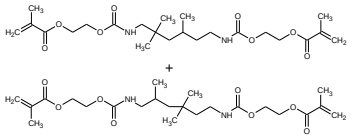
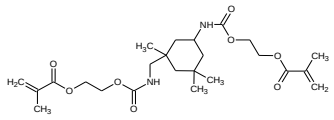
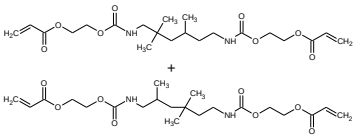
FUNCTIONAL URETHANES								
R1095	U-793	869488-57-3 920758-62-9 902742-80-9 (Y)	Urethane resin functionalized with a methacrylate and an epoxy	Unavailable	• Low color • Low cure shrinkage • Thermal stability • Tough	Light Yellow Tint Liquid	6,500 (50°C)	• Dental
R1102	U-835	869488-57-3 1003557-45-6 1003612-76-7 (Y-LVE)	Urethane resin functionalized with acrylate and methacrylate end groups	Unavailable	• Low modulus • Excellent hydrolytic resistance • High adhesion * • Adhesion to metals • Flexibilizer	Light Yellow Liquid	20,000	• Dental • Moisture resistant coatings
R1216	U-347	1371570-15-8 (N)	Phenyl glycerol urethane dimethacrylate (PGDMA)		• Low cure shrinkage • Colorless • Good refractive index • Not bisphenol A based	Clear Colorless Liquid	9,500	• Dental • Moisture resistant coatings
R1228	U-471	72869-86-4 (Y)	TMDI urethane dimethacrylate monomer		• Low color • Low cure shrinkage	Slight Yellow Liquid	8,000	• Dental
R1230	U-483	N/A (N)	IPDI urethane dimethacrylate		• Low viscosity • Low cure shrinkage • Colorless • Not bisphenol A based	Clear Colorless Liquid	5,000	• Dental • Moisture resistant coatings • Light cure coatings
R1266	U-443	67910-48-9 (N)	TMDI urethane diacrylate monomer		• Excellent Curing Properties	Clear Colorless Oil	5,500	• Light-cured coating resins

PRODUCT SELECTOR GUIDE

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FORMULATED PRODUCTS								
R1353	DMI-2575	Mixture (Y)	Unique low viscosity liquid bismaleimide based formulation suitable for use as a base resin system for spray applications	Mixture	• Pre-catalyzed • Extended pot-life (< 6mo. @ room temp) • Hydrophobic • Solvent free • Superior thermal stability • Does not require refrigerated shipping	Amber liquid	1400 ± 300	• Spray coating applications
R1397	DMI-3006A	Mixture (Y)	Modified polyimide based negative type photoresist	Mixture	• Low modulus • Very high electrical reliability • UV cured-low thermal requirements • Low cure shrinkage • High heat resistance • Good electrical properties	Amber liquid	250	• Wafer buffer coating
R1398	DMI-2555	Mixture (Y)	A BMI-based coating for dispense applications	Mixture	• Pre-catalyzed • Low modulus • Hydrophobic • Excellent hydrolytic resistance • Low stress • Adhesion to metals • Flexibilizer	Yellow to Dark Amber Liquid	900 ± 200	• Die top coating applications

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IMIDE-LINKED								
R1363	ILR-1363	Mixture (N)	A high molecular weight, curable oligomer mixture suitable for use as the base resin in a variety of microelectronic assembly applications	Unavailable	• High strength • Flexible • Hydrophobic • High heat resistance • Good electrical properties	Amber liquid	750	• A polyimide (PI) replacement resin
R1399	ILR-1399	3027864-14-5 (N)	A proprietary high molecular weight functionalized polyimide designed specifically to resist degradation when exposed to elevated temperatures for extended durations	Unavailable	• Thermally curable • Tough • Superior thermal stability • Hydrophobic	Amber liquid	15,000 @ 25% Solids	• For use in LED assembly applications or where high temperature stability is required.
R1400	ILR-1400	2489312-38-9 (N)	High molecular weight non-functionalized polyimide with excellent physical properties	Unavailable	• Very Flexible film • Good thermal stability (Td = > 400°C) • Good wetting property post b-stage on copper foil • Superior dielectric properties • Low water absorption • Soluble in most aromatic and aliphatic solvents	Amber liquid	1,500 @ 15% Solids	• For use where flexibility and good electrical properties are required
R1401	ILR-1401	Mixture (Y)	A high molecular weight, curable oligomer mixture suitable for use as the base resin in a variety of microelectronic assembly applications	Unavailable	• Very low material shrinkage • Flexible / high strength • Curability & very low modulus • Hydrophobic / low water absorption	Amber liquid	5,000 @ 20% Solids	• For use in applications that require high temperature resin performance such as CCL
R1402	ILR-1402	Mixture (Y)	A high molecular weight, curable oligomer mixture suitable for use as the base resin in a variety of microelectronic assembly applications	Unavailable	• Very low material shrinkage • Flexible / high strength • Curability & very low modulus • Hydrophobic / low water absorption	Amber liquid	4,000 @ 20% Solids	• For use in applications that require high temperature resin performance such as CCL
R1457	ILR-1457	3027864-14-5 (N)	A proprietary high molecular weight functionalized polyimide designed specifically to resist degradation when exposed to elevated temperatures for extended durations	Unavailable	• Thermally curable • Tough • Superior thermal stability • Hydrophobic	Amber liquid	2,500 @ 25% Solids	• For use in high temperature adhesive applications

ALL DATA PROVIDED FOR REFERENCE ONLY AND MAY VARY BY TEST METHOD

* Various substrates

** Many of the structures are an idealized representation of a statistical distribution

*** Supercooled

**** Storage at < 25°C will result in precipitation of some solids. The fully liquid state can be regenerated by warming to 40°C until all solids dissolve

LVE Material manufactured under Low Volume Exemption (LVE) in compliance with Section 5(h)(4) of the Toxic Substances Control Act (TSCA), 15 U.S.C.

TO PLACE AN ORDER, REQUEST SAMPLES, OR TO SPEAK WITH US ABOUT DEVELOPING A PRODUCT FOR YOUR CHEMICAL NEEDS, CONTACT US AT 858-348-1122